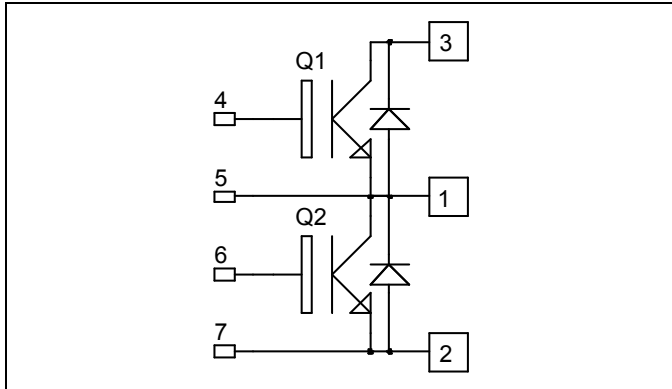


**Phase leg  
Trench + Field Stop IGBT  
Power Module**

**$V_{CES} = 1700V$   
 $I_C = 75A @ T_c = 80^\circ C$**

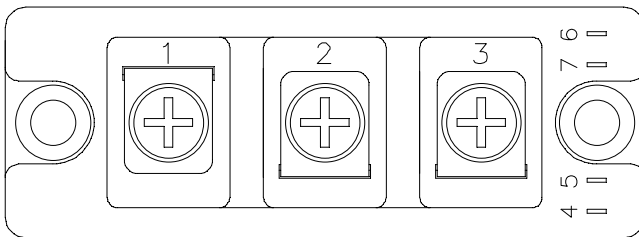


### Application

- Welding converters
- Switched Mode Power Supplies
- Uninterruptible Power Supplies
- Motor control

### Features

- Trench + Field Stop IGBT Technology
  - Low voltage drop
  - Low tail current
  - Switching frequency up to 20 kHz
  - Soft recovery parallel diodes
  - Low diode VF
  - Low leakage current
  - RBSOA and SCSOA rated
- Kelvin emitter for easy drive
- High level of integration
- M5 power connectors



### Benefits

- Outstanding performance at high frequency operation
- Stable temperature behavior
- Very rugged
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- Easy paralleling due to positive TC of VCESat
- RoHS Compliant

### Absolute maximum ratings

Symbol	Parameter		Max ratings	Unit
$V_{CES}$	Collector - Emitter Breakdown Voltage		1700	V
$I_C$	Continuous Collector Current	$T_C = 25^\circ C$	130	A
		$T_C = 80^\circ C$	75	
$I_{CM}$	Pulsed Collector Current	$T_C = 25^\circ C$	150	
$V_{GE}$	Gate - Emitter Voltage		$\pm 20$	V
$P_D$	Maximum Power Dissipation	$T_C = 25^\circ C$	465	W
RBSOA	Reverse Bias Safe Operating Area	$T_j = 125^\circ C$	150A @ 1600V	

**CAUTION:** These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on [www.microsemi.com](http://www.microsemi.com)

All ratings @  $T_j = 25^\circ\text{C}$  unless otherwise specified

**Electrical Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$I_{CES}$	Zero Gate Voltage Collector Current	$V_{GE} = 0\text{V}, V_{CE} = 1700\text{V}$			250	$\mu\text{A}$
$V_{CE(sat)}$	Collector Emitter Saturation Voltage	$V_{GE} = 15\text{V}$ $I_C = 75\text{A}$	$T_j = 25^\circ\text{C}$	2.0	2.4	V
			$T_j = 125^\circ\text{C}$	2.4		
$V_{GE(th)}$	Gate Threshold Voltage	$V_{GE} = V_{CE}, I_C = 3\text{mA}$	5.0	5.8	6.5	V
$I_{GES}$	Gate – Emitter Leakage Current	$V_{GE} = 20\text{V}, V_{CE} = 0\text{V}$			600	nA

**Dynamic Characteristics**

Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$C_{ies}$	Input Capacitance	$V_{GE} = 0\text{V}$		6800		pF
$C_{oes}$	Output Capacitance	$V_{CE} = 25\text{V}$		277		
$C_{res}$	Reverse Transfer Capacitance	$f = 1\text{MHz}$		220		
$Q_G$	Gate charge	$V_{GE} = \pm 15\text{V}, I_C = 75\text{A}$ $V_{CE} = 900\text{V}$		0.85		$\mu\text{C}$
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ( $25^\circ\text{C}$ )		280		ns
$T_r$	Rise Time	$V_{GE} = 15\text{V}$ $V_{Bus} = 900\text{V}$		80		
$T_{d(off)}$	Turn-off Delay Time	$I_C = 75\text{A}$		850		
$T_f$	Fall Time	$R_G = 18\Omega$		120		
$T_{d(on)}$	Turn-on Delay Time	Inductive Switching ( $125^\circ\text{C}$ )		300		ns
$T_r$	Rise Time	$V_{GE} = 15\text{V}$ $V_{Bus} = 900\text{V}$		100		
$T_{d(off)}$	Turn-off Delay Time	$I_C = 75\text{A}$		1000		
$T_f$	Fall Time	$R_G = 18\Omega$		200		
$E_{on}$	Turn-on Switching Energy	$V_{GE} = 15\text{V}$ $V_{Bus} = 900\text{V}$	$T_j = 125^\circ\text{C}$	27		mJ
$E_{off}$	Turn-off Switching Energy	$I_C = 75\text{A}$ $R_G = 18\Omega$	$T_j = 125^\circ\text{C}$	24.5		
$I_{sc}$	Short Circuit data	$V_{GE} \leq 15\text{V}; V_{Bus} = 1000\text{V}$ $t_p \leq 10\mu\text{s}; T_j = 125^\circ\text{C}$		300		A

**Reverse diode ratings and characteristics**

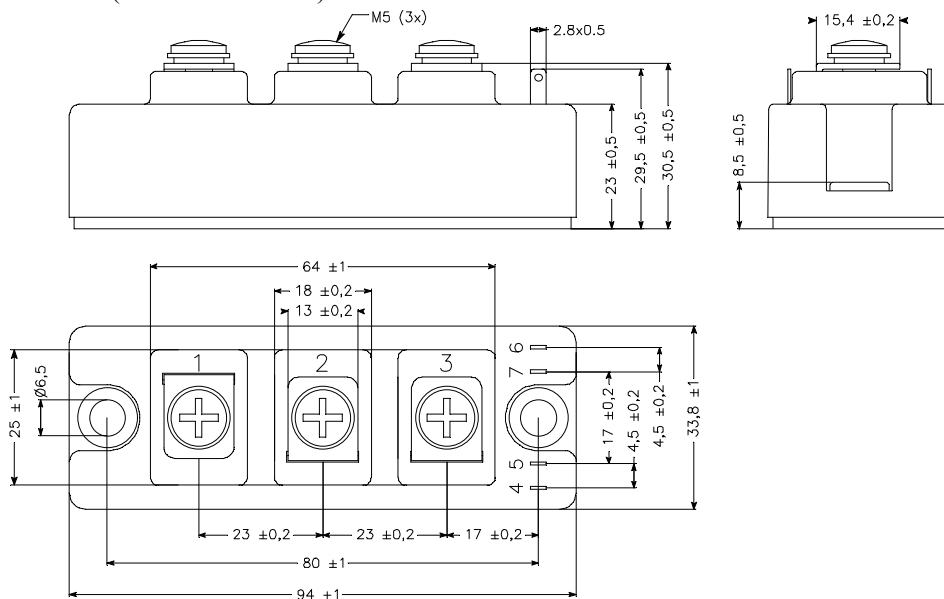
Symbol	Characteristic	Test Conditions	Min	Typ	Max	Unit
$V_{RRM}$	Maximum Peak Repetitive Reverse Voltage		1700			V
$I_{RM}$	Maximum Reverse Leakage Current	$V_R = 1700\text{V}$	$T_j = 25^\circ\text{C}$		250	$\mu\text{A}$
			$T_j = 125^\circ\text{C}$		500	
$I_F$	DC Forward Current		$T_c = 80^\circ\text{C}$	75		A
$V_F$	Diode Forward Voltage	$I_F = 75\text{A}$	$T_j = 25^\circ\text{C}$	1.8	2.2	V
			$T_j = 125^\circ\text{C}$	1.9		
$t_{rr}$	Reverse Recovery Time	$I_F = 75\text{A}$ $V_R = 900\text{V}$ $di/dt = 800\text{A}/\mu\text{s}$	$T_j = 25^\circ\text{C}$	410		ns
			$T_j = 125^\circ\text{C}$	520		
$Q_{rr}$	Reverse Recovery Charge		$T_j = 25^\circ\text{C}$	19		$\mu\text{C}$
			$T_j = 125^\circ\text{C}$	31		
$E_{rr}$	Reverse Recovery Energy		$T_j = 25^\circ\text{C}$	9		mJ
			$T_j = 125^\circ\text{C}$	17.5		

## Thermal and package characteristics

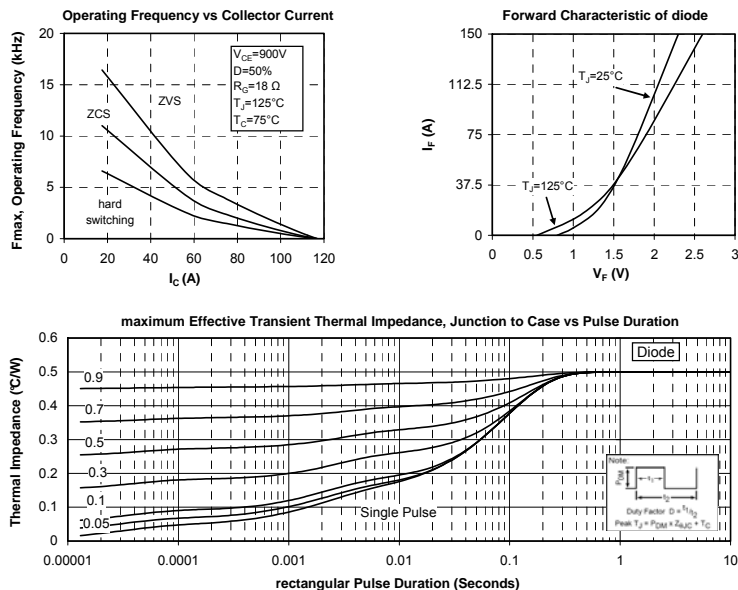
Symbol Characteristic

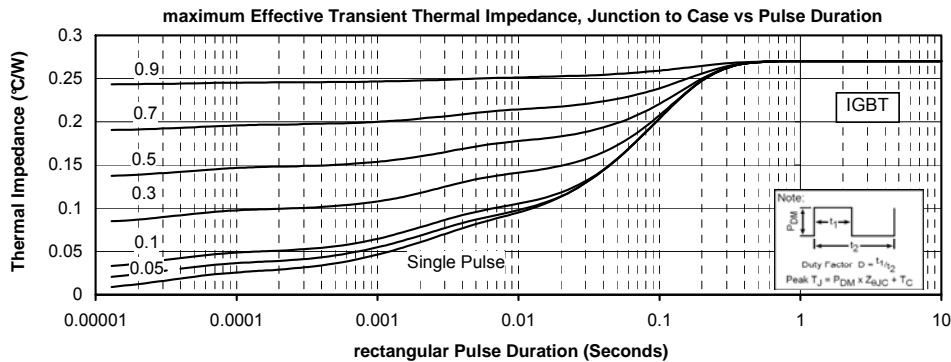
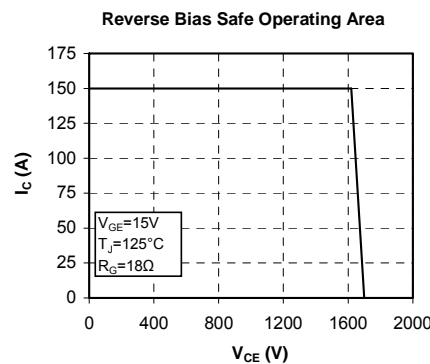
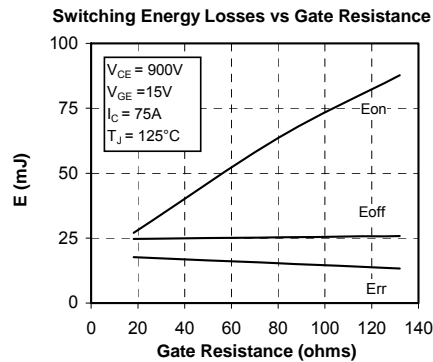
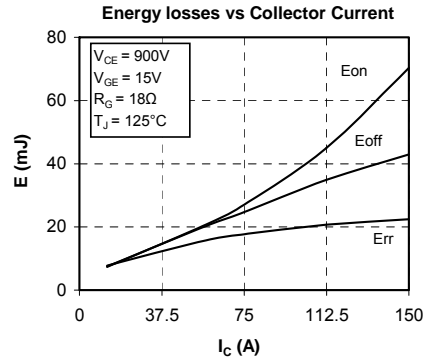
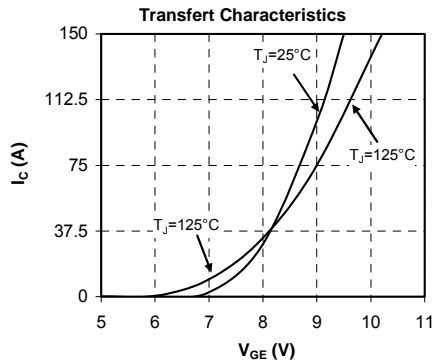
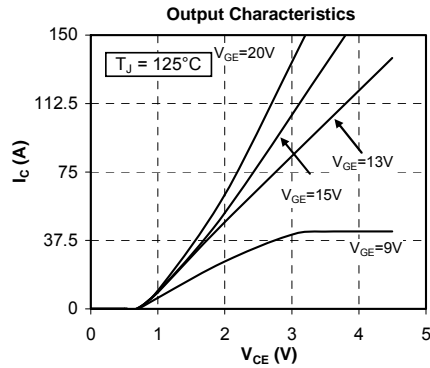
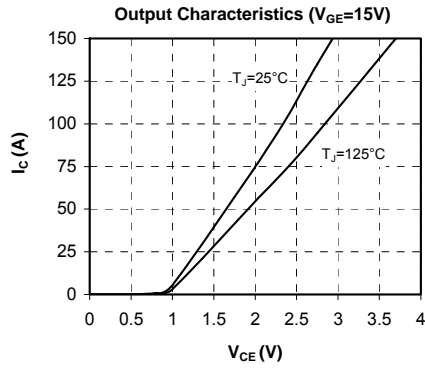
			Min	Typ	Max	Unit
$R_{thJC}$	Junction to Case Thermal Resistance	IGBT			0.27	°C/W
		Diode			0.5	
$V_{ISOL}$	RMS Isolation Voltage, any terminal to case t=1 min, I isol<1mA, 50/60Hz		4000			V
$T_J$	Operating junction temperature range		-40		150	°C
$T_{STG}$	Storage Temperature Range		-40		125	
$T_C$	Operating Case Temperature		-40		125	
Torque	Mounting torque	For terminals	M5	2	3.5	N.m
		To Heatsink	M6	3	5	
Wt	Package Weight				180	g

## D1 Package outline (dimensions in mm)



## Typical Performance Curve





Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 6,939,743 7,352,045 5,283,201 5,801,417 5,648,283 7,196,634 6,664,594 7,157,886 6,939,743 7,342,262 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.